

LAUNCHING PHOTO HEAD FOR ADVANCED PACKAGING - LLS 04

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Visitech is proud to present the LLS 04 on the Productronica in Munchen now in November 2017. The LUXBEAM® Lithography system, a subsystem for Direct Imaging machine builders, is already used in solder mask and inner/outer layer applications with line/space down to 10 μm .

The new LLS 04 can achieve a 4 μm line/space and comes with a powerful 405 nm light source. Further, it comes together with an upgraded fast and accurate autofocus and will be capable of delivering state-of-the-art throughput.

«With the new LLS 04 we also cover more of the advanced packaging market in DI», says Director

of Business Development Oyvind Tafjord.

Learn more about our subsystems for advanced packaging:

[direct imaging lithography](#)